

10/676,443

PATENT APPLICATION

Sheet 1 of 1

FORM PTO-1449

LIST OF PATENTS AND PUBLICATIONS FOR
APPLICANT'S INFORMATION DISCLOSURE
STATEMENT

(Use several sheets if necessary)

ATTY. DOCKET NO.

200308123-4

APPLICATION NO.

10/676,443

CONFIRMATION NO.

APPLICANT

ATAKOV, et al

FILING DATE

10/01/2003

GROUP

3729

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	PUBLICATION DATE	NAME	Pages, Columns, Lines Where Relevant Passages or Figures Appear
<i>Cja</i>	1A	5,973,402	10/1999	Shinriki, et al	
<i>Cja</i>	1B	5,889,233	03/1999	Shimeto, et al	
<i>Cja</i>	1C	5,760,476	06/1998	Varker, et al	
<i>Cja</i>	1D	5,745,984	05/1998	Cole, Jr., et al	
<i>Cja</i>	1E	5,666,722	09/1997	Tamm, et al	
<i>Cja</i>	1F	5,663,102	09/1997	Park	
<i>Cja</i>	1G	5,600,884	02/1997	Kondo, et al	
<i>Cja</i>	1H	5,439,731	08/1995	Lietal	
<i>Cja</i>	1I	5,363,550	11/1994	Aitken, et al	
<i>Cja</i>	1J	5,329,695	07/1994	Traskos, et al	
<i>Cja</i>	1K	5,306,872	04/1994	Kordus, et al	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	PUBLICATION DATE	NAME OF PATENTEE OR APPLICANT	Pages/Columns/Lines Where Relevant Passages/Figures Appear	Check if Translation attached
	1L					
	1M					
	1N					
	1O					
	1P					

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

<i>Cja</i>	1Q	"Electromigration in Thin Aluminum Films on Titanium Nitride", Journal of Applied Physics, Vol. 47, No. 4, April 1976, pp1203-1208
<i>Cja</i>	1R	"An increase of the Electromigration Reliability of Ohmic Contacts by Enhancing Backflow Effect", Institute of Electrical Engineers (IEEE), 1995, Zhang, W. et al, pp365-370
<i>Cja</i>	1S	"Evidence of the Electromigration Short-Length Effect in Aluminum-Based Metallurgy with Tungsten Diffusion Barriers", Mat. Res. Soc. Symp. Proc., vol309, 1993 Materials Research Society, pp. 141-149

EXAMINER

C. J. Archer

DATE CONSIDERED

3/4/03

PATENT APPLICATION

Sheet 2 of 2

FORM PTO-1449

LIST OF PATENTS AND PUBLICATIONS FOR
APPLICANT'S INFORMATION DISCLOSURE
STATEMENT

(Use several sheets if necessary)

ATTY. DOCKET NO.

200308123-4

APPLICATION NO.

10/676,443

CONFIRMATION NO.

APPLICANT

ATAKOV, et al

FILING DATE

10/01/2003

GROUP

3729

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	PUBLICATION DATE	NAME	Pages, Columns, Lines Where Relevant Passages or Figures Appear
Cja	1A	4,861,640	08/1998	Guroi	_____
Cja	1B	4,296,424	10/1981	Shibasaki et al	_____
	1C				
	1D				
	1E				
	1F				
	1G				
	1H				
	1I				
	1J				
	1K				

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	PUBLICATION DATE	NAME OF PATENTEE OR APPLICANT	Pages/Columns/Lines Where Relevant Passages/Figures Appear	Check if Translation attached
	1L					
	1M					
	1N					
	1O					
	1P					

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

Cja	1Q	""Permitted Electromigration of Tungsten-Plug vias in Chain for Test Structure with Short Inter-Plug Distance", T. Aoki, et al, VMIC Conference, June 7-8, 1994 ISMIC				
	1R					
	1S					

EXAMINER

C. J. Arber

DATE CONSIDERED

8/11/05